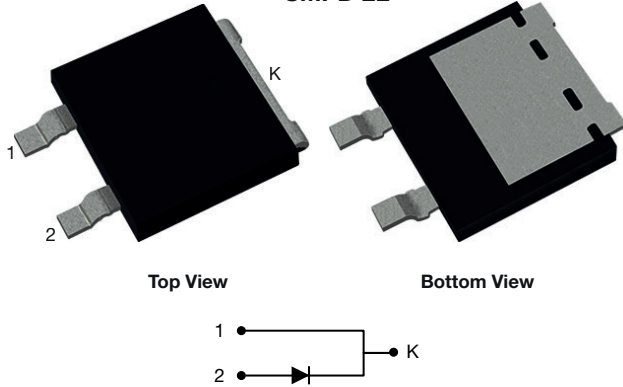


Surface-Mount ESD Capability Rectifiers

eSMP® Series SMPD 2L



FEATURES

- Creepage and clearance distance 3.6 mm minimum
- Very low profile - typical height of 1.7 mm
- Ideal for automated placement
- Oxide planar chip junction
- Low forward voltage drop
- ESD capability
- AEC-Q101 qualified available
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

 AUTOMOTIVE
GRADE
Available

RoHS
COMPLIANT
HALOGEN
FREE

LINKS TO ADDITIONAL RESOURCES



TYPICAL APPLICATIONS

General purpose, power line polarity protection, in both consumer and automotive on board charger (OBC) applications.

MECHANICAL DATA

Case: SMPD 2L

Molding compound meets UL 94 V-0 flammability rating
Base P/N-M3 - halogen-free, RoHS-compliant, and industry grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

Polarity: as marked

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	10 A
V_{RRM}	400 V, 600 V
I_{FSM}	110 A
V_F at $I_F = 10$ A ($T_J = 125$ °C)	0.96 V
I_R	15 μ A
T_J max.	175 °C
Package	SMPD 2L
Circuit configuration	Single

MAXIMUM RATINGS ($T_A = 25$ °C unless otherwise noted)				
PARAMETER	SYMBOL	SE10DTG	SE10DTJ	UNIT
Device marking code		SE10DTG	SE10DTJ	V
Maximum repetitive peak reverse voltage	V_{RRM}	400	600	V
Maximum DC forward current	$I_F^{(1)}$	10		A
	$I_F^{(2)}$	2.9		
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I_{FSM}	110		A
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +175		°C

Notes

(1) With heatsink

(2) Free air, mounted on recommended copper pad area



ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	$I_F = 5\text{ A}$	$T_J = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.95	-	V
	$I_F = 10\text{ A}$			1.04	1.15	
	$I_F = 5\text{ A}$	$T_J = 125\text{ }^\circ\text{C}$		0.85	-	
	$I_F = 10\text{ A}$			0.96	1.10	
Reverse current	Rated V_R	$T_J = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	-	15	μA
		$T_J = 125\text{ }^\circ\text{C}$		22	150	
Typical reverse recovery time	$I_F = 0.5\text{ A}$, $I_R = 1.0\text{ A}$, $I_{rr} = 0.25\text{ A}$		t_{rr}	3000	-	ns
Typical junction capacitance	4.0 V, 1 MHz		C_J	67	-	pF

Notes

- (1) Pulse test: 300 μs pulse width, 1 % duty cycle
(2) Pulse test: Pulse width $\leq 40\text{ ms}$

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Thermal resistance	$R_{\theta JA}^{(1)(2)}$	60	75	$^\circ\text{C/W}$
	$R_{\theta JM}^{(3)}$	1.8	2.2	

Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient: $dP_D/dT_J < 1/R_{\theta JA}$
(2) Thermal resistance junction-to-ambient to follow JEDEC[®] 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint
(3) Thermal resistance junction-to-mount to follow JEDEC[®] 51-14 transient dual interface test method (TDIM)

IMMUNITY TO ELECTRICAL STATIC DISCHARGE TO THE FOLLOWING STANDARDS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)					
STANDARD	TEST TYPE	TEST CONDITIONS	SYMBOL	CLASS	VALUE
AEC-Q101-001	Human body model (contact mode)	$C = 100\text{ pF}$, $R = 1.5\text{ k}\Omega$	V_C	H3B	$> 8\text{ kV}$

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
SE10DTJ-M3/I	0.52	I	2000 / reel	13" diameter plastic tape and reel
SE10DTJHM3/I ⁽¹⁾	0.52	I	2000 / reel	13" diameter plastic tape and reel

Note

- (1) AEC-Q101 qualified

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

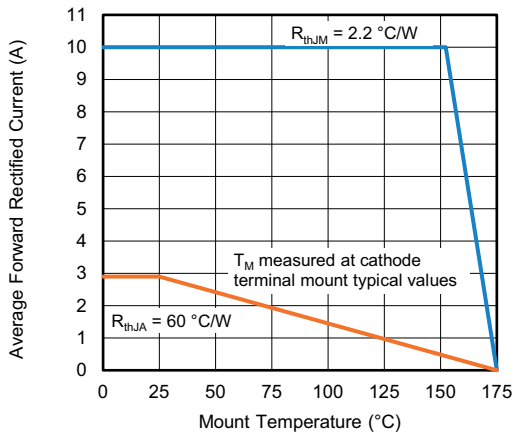


Fig. 1 - Forward Current Derating Curve

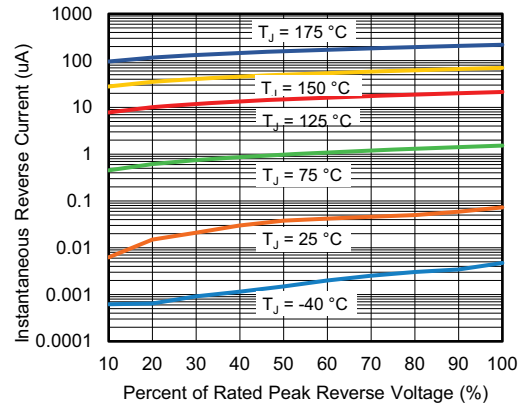


Fig. 4 - Typical Reverse Leakage Characteristics

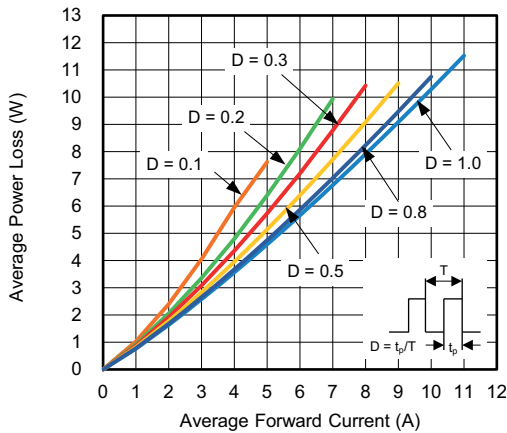


Fig. 2 - Forward Power Loss Characteristics

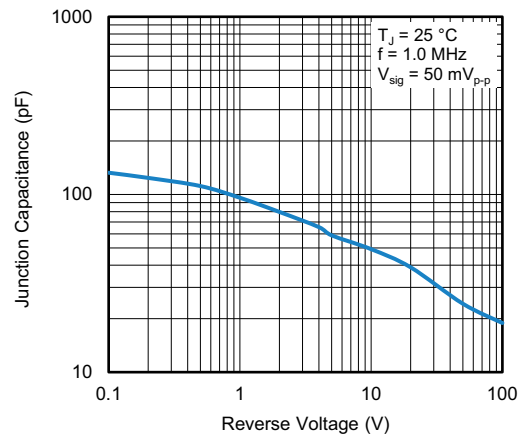


Fig. 5 - Typical Junction Capacitance

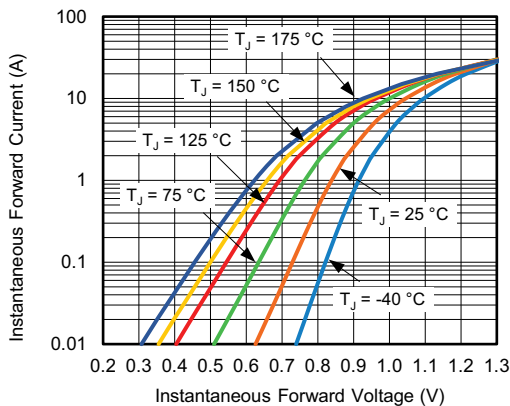


Fig. 3 - Typical Instantaneous Forward Characteristics

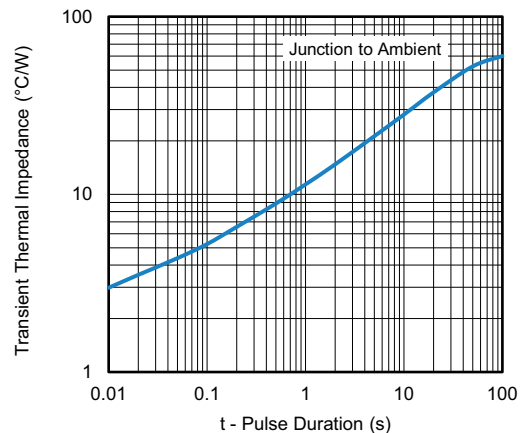
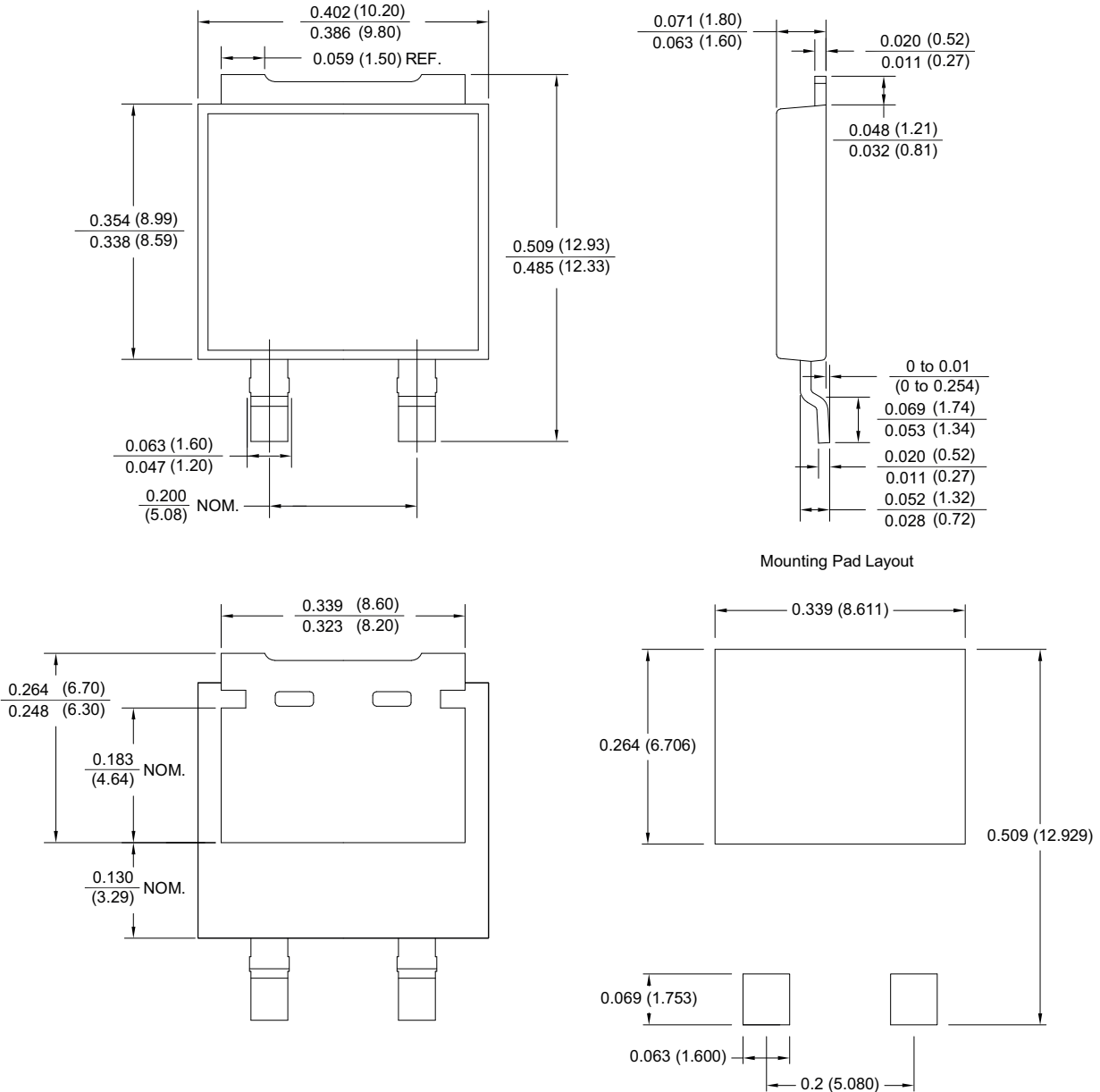


Fig. 6 - Typical Transient Thermal Impedance



PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SMPD 2L



Note

- The suggested mounting pad layout is provided for reference only, as actual pad layouts may vary depending on application



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